

OL-TFA9881UK

Wafer level chip-size package; 9 bumps; 1.3 x 1.3 x 0.6 mm

8 February 2016

Package information

1. Package summary

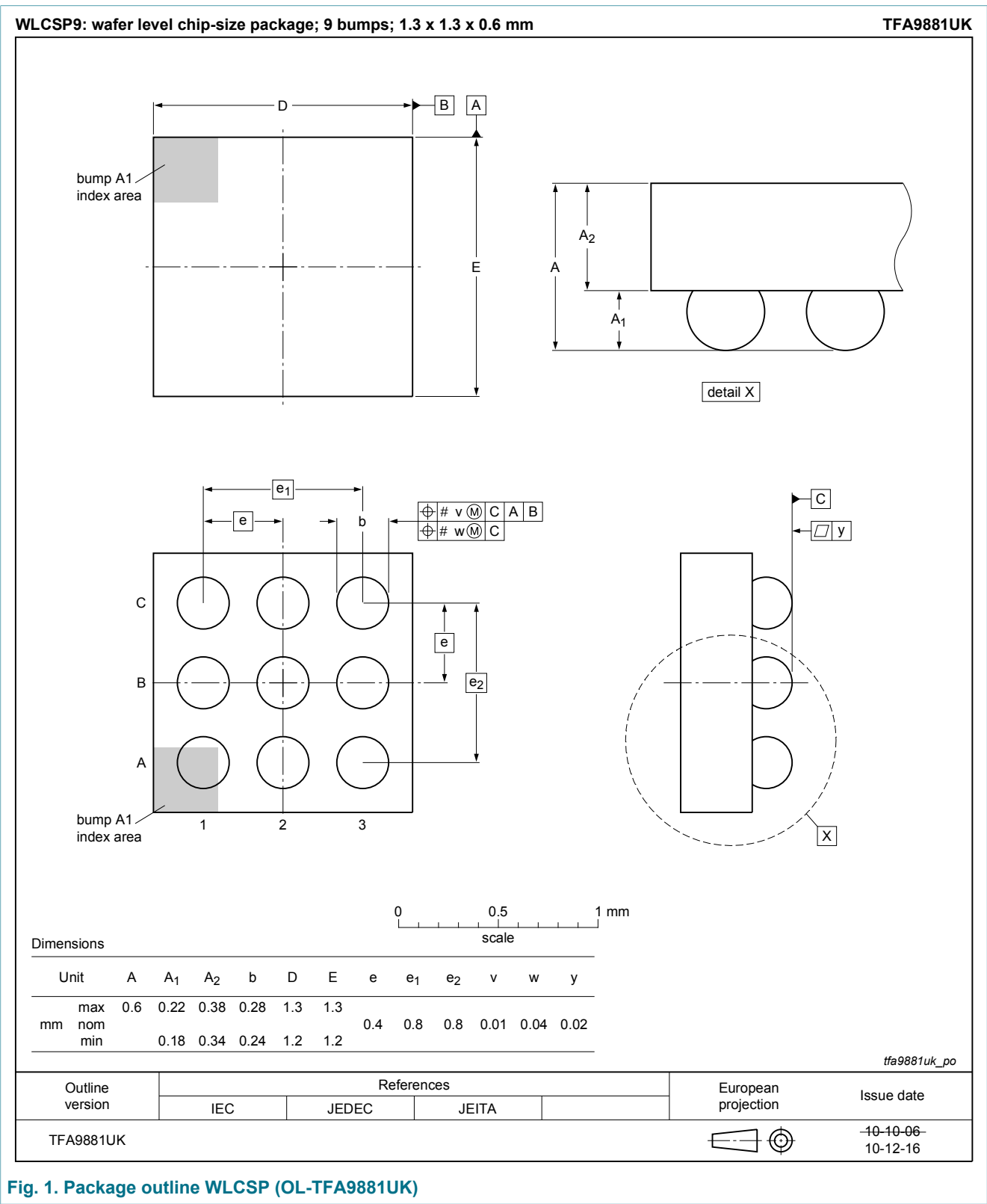
Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	6-10-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.2	-	[tbd]	1.3	mm
E	package width		1.2	-	[tbd]	1.3	mm
A	seated height		[tbd]	-	[tbd]	0.6	mm
A ₂	package height		0.34	-	[tbd]	0.38	mm
n ₂	actual quantity of termination		-	-	9	-	



2. Package outline



3. Legal information

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